Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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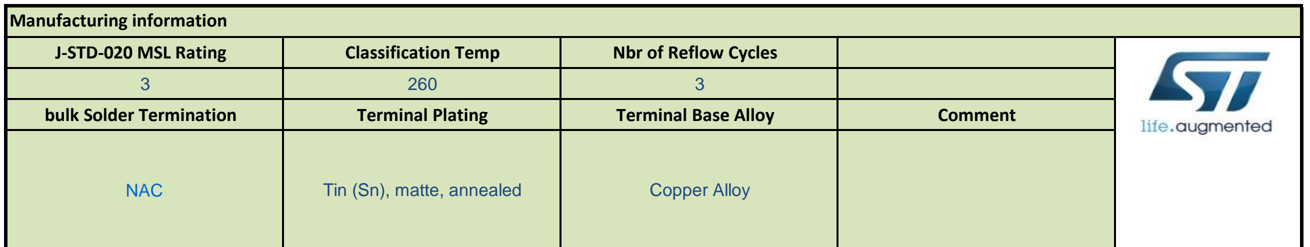
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F469IIT6	Y11T*434XXXA	A	9991	2017-02-10
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	1650.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	24x24x1.4	176	L Bend	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**TRUE**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**Y11T*434XXXA**				5999998.0	1000000.0
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	21.181	mg	supplier	die	Silicon (Si)	7440-21-3		20.001	mg	944290	12122
					metallization	Aluminium (Al)	7429-90-5		0.082	mg	3871	50
					metallization	Copper (Cu)	7440-50-8		0.536	mg	25306	325
					metallization	Cobalt (Co)	7440-48-4		0.002	mg	94	1
					metallization	Tantalum (Ta)	7440-25-7		0.075	mg	3541	45
					metallization	Tungsten (W)	7440-33-7		0.241	mg	11378	146
					Passivation	Silicon Nitride	12033-89-5		0.063	mg	2974	38
					Passivation	Silicon Oxide	7631-86-9		0.181	mg	8545	110
Encapsulation	M-011 Other inorganic materials	938.546	mg	supplier	Molding Compound	Epoxy Resin A	Proprietary		41.840	mg	44580	25358
					Molding Compound	Epoxy Resin B	Proprietary		41.840	mg	44580	25358
					Molding Compound	Phenol Resin	Proprietary		62.760	mg	66869	38036
					Molding Compound	Carbon Black	1333-86-4		4.184	mg	4458	2536
					Molding Compound	Silica Fused	60676-86-0		787.922	mg	839513	477528
Leadframe	M-011 Other inorganic materials	666.052	mg	supplier	Alloy	Copper (CU)	7440-50-8		626.402	mg	940470	379638
					Alloy	Nickel (Ni)	7440-02-0		24.780	mg	37204	15018
					Alloy	Silicon (Si)	7440-21-3		5.370	mg	8062	3255
					Alloy	Silver (Ag)	7440-22-4		8.260	mg	12401	5006
					Alloy	Magnesium (Mg)	7439-95-4		1.240	mg	1862	752
Die Attach	M-011 Other inorganic materials	3.010	mg	supplier	Glue	Silver Flake	7440-22-4		2.330	mg	774086	1412
					Glue	Epoxy Acylate	15625-89-5		0.150	mg	49834	91
					Glue	Substiyuted Polyamine	68490-66-4		0.050	mg	16611	30
					Glue	Bisphenol F	28064-14-4		0.300	mg	99668	182
					Glue	2-Ethylhexyl glycidyl ether	2461-15-6		0.180	mg	59801	109
Bonding wire	M-011 Other inorganic materials	2.510	mg	supplier	Bonding wire	Au	7440-57-5		2.480	mg	988048	1503
					Bonding wire	Pd	7440-05-3		0.030	mg	11952	18
Finishing	M-011 Other inorganic materials	18.700	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		18.700	mg	1000000	11333